



BK7236M Datasheet

DS-BK7236M-E01 V1.0

2025/1/6

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1. Features

Wi-Fi

- IEEE 802.11b/g/n/ax 1x1 compliant
- 20/40 MHz channel bandwidth for 2.4 GHz
- Supports downlink Multi-User Multiple-Input Multiple-Output (DL MU-MIMO)
- Supports Orthogonal Frequency Division Multiple Access (OFDMA)
- Supports Target Wake Time (TWT)
- TX and RX Low-Density Parity Check (LDPC) support for extended range
- WPA/WPA2/WPA3-Personal support for enhanced security
- Supports STA and SoftAP modes
- Supports concurrent SoftAP + STA
- TX power up to +21 dBm
- RX sensitivity -98 dBm

Bluetooth Low Energy

- Bluetooth Low Energy (LE) 5.4
- Supports Bluetooth Low Energy 1 Mbps, 2 Mbps, and long range (125 kbps and 500 kbps)
- Supported Bluetooth Low Energy features: LE Audio, Angle of Arrival (AoA) and Angle of Departure (AoD) direction finding, 2 Mbps, advertising extensions, and long range
- Supports an antenna array with up to 16 antennas for precise positioning

Core

- Armv8-M STAR-MC1 MCU at up to 320 MHz:
 - Double-precision floating-point unit (FPU)
 - 16 KB ITCM + 16 KB DTCM
 - Embedded TrustZone
 - Supports DSP instructions with SIMD
 - 3.84 CoreMark/MHz
- UART flash download
- Serial Wire Debug (SWD) interface

Memory

- 4 MB SiP flash
- 640 KB Share SRAM
- 64 KB ROM
- eFuse

Security

The BK7236M integrates the IoT Platform Security Suite (IPSS) for cryptograph and system security control. The key features of the IPSS include:

- Secure boot
- Secure debug
- Secure connection
- Firmware Over-The-Air (FOTA)
- Provisioning
- TEE_M
- TrustEngine, which includes the following features:
 - Symmetric schemes, AES-ECB/CBC/CTR/CBC-MAC/CMAC/CCM/GCM (key size 128-bit, 192-bit and 256-bit)
 - Symmetric schemes, SM4-ECB/CBC/CTR/CBC-MAC/CMAC/CCM/GCM
 - Digest schemes, SHA1/224/256
 - Digest scheme, SM3
 - Asymmetric schemes, RSA 1024/2048/3072/4096 and ECCP 192/224/256/384/512/521
 - Asymmetric scheme, SM2
 - Key ladder for key management
 - Lifecycle management
 - True random number generator

Clock Management

- External oscillators: 26 MHz crystal oscillator (XTALH), 32 kHz crystal oscillator (XTALL)
- Internal oscillators: 26–360 MHz digitally controlled oscillator (DCO), 32 kHz ring oscillator (ROSC)
- 320/480 MHz PLL (DPLL)
- Audio PLL (APLL)



Power Management

- 2.0 to 4.35 V VBAT supply
- On-chip Power-On Reset (POR) and Brown-Out Detector (BOD)
- Embedded buck (DC-DC) converters and LDO regulators
- Low power consumption:
 - Active mode RX: 17.5 mA
 - Sleep mode: 43 μ A
 - Deep sleep mode: 16 μ A
 - Shutdown mode: 2.5 μ A

Peripherals

- 19 GPIOs
- 1x SPI
- 3x UART, 1 with flash download support
- 1x SDIO
- 1x I2C
- 1x high-speed USB2.0 (HS)
- 1x LIN controller
- 2x general-purpose DMA controller (GDMA), each with 8 channels
- 8x 32-bit PWM channel
- 1x DMIC
- 12-bit AUX ADC, up to 5 channels
- 6x 32-bit general-purpose timer
- 2x watchdog timer
- 1x real-time counter (RTC)
- 1x temperature sensor
- 1x touch sensor, 4 touch sensing I/Os

Packaging

- QFN40 package, 5 x 5 mm
- Operating temperature range: -40 to +105 °C

Applications

- Home appliance



- Refrigerator
- Air conditioner
- Thermostat
- Washing machine
- Robot cleaner
- Smart plug
- Smart lighting
 - Light bulb
 - Light switch
 - Ceiling light
 - Stand light
- Others
 - Remote controller
 - Toy
 - Drone
 - Industrial terminal
 - Factory automation sensor/switch
 - Smart meter
 - Payment terminal
 - Industrial computer
 - Medical devices
 - Kitchen appliances
 - Home automation switch/sensor
 - Door lock
 - Door camera

2. Overview

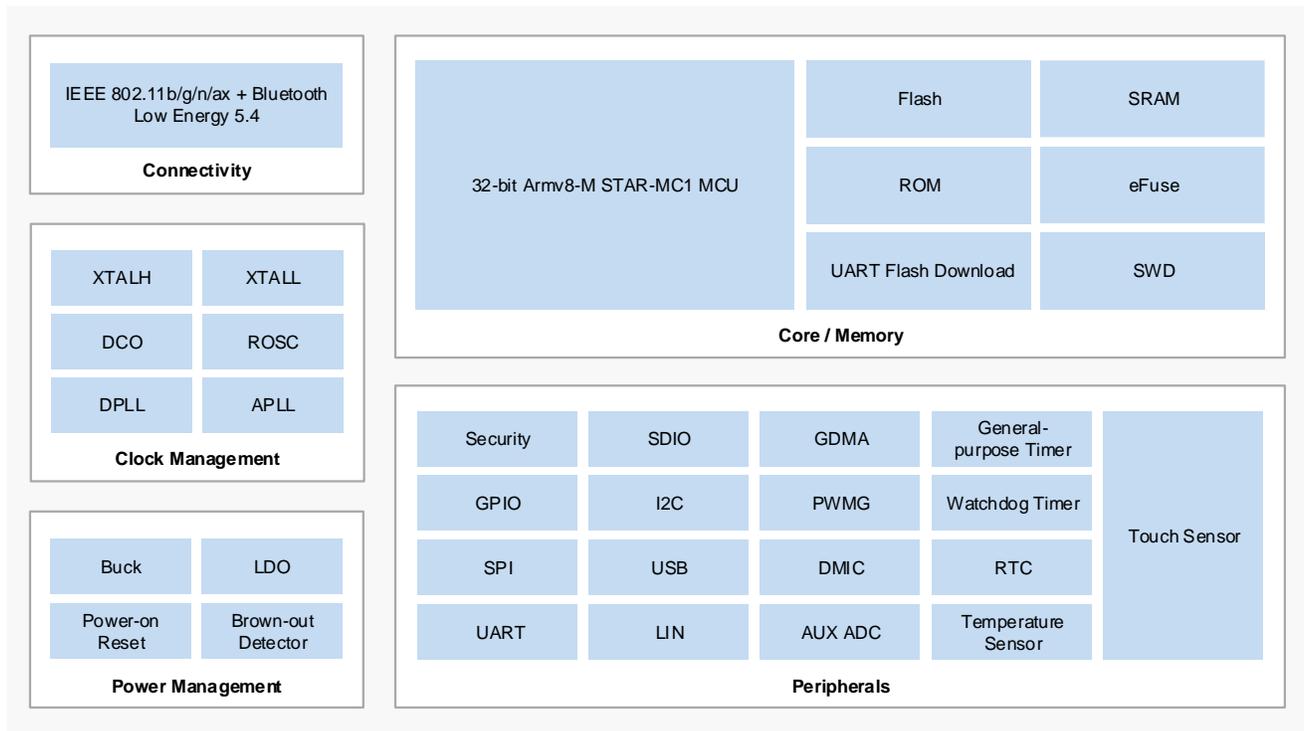
The BK7236M is a highly integrated 1x1 single-band 2.4 GHz Wi-Fi 6 (802.11b/g/n/ax) and Bluetooth Low Energy (LE) 5.4 combo solution designed for applications that require high security and abundant resources. The integration of a 32-bit Armv8-M STAR-MC1 MCU and a comprehensive set of peripherals makes the BK7236M ideal for advanced Internet of Things (IoT) applications.

The BK7236M provides state-of-the-art security based on a powerful security architecture. The BK7236M integrates a IoT Platform Security Suite (IPSS) for cryptograph and system security control. The IPSS embeds all-round and robust security features to set up a top-secret execution environment for IoT devices.

Using advanced design techniques and ultra-low power process technology, the BK7236M delivers high integration, efficient security, and minimal power consumption for a wide range of advanced IoT applications.

Figure 2-1 shows the general block diagram of the BK7236M.

Figure 2-1 BK7236M Block Diagram



3. Pin Descriptions

The BK7236M provides Wi-Fi and Bluetooth LE functionality in a 5 x 5 mm, 40-pin QFN package.

3.1 QFN40 Pin Descriptions

Figure 3-1 shows the pin assignments of the QFN40 package.

Figure 3-1 QFN40 Pin Assignments

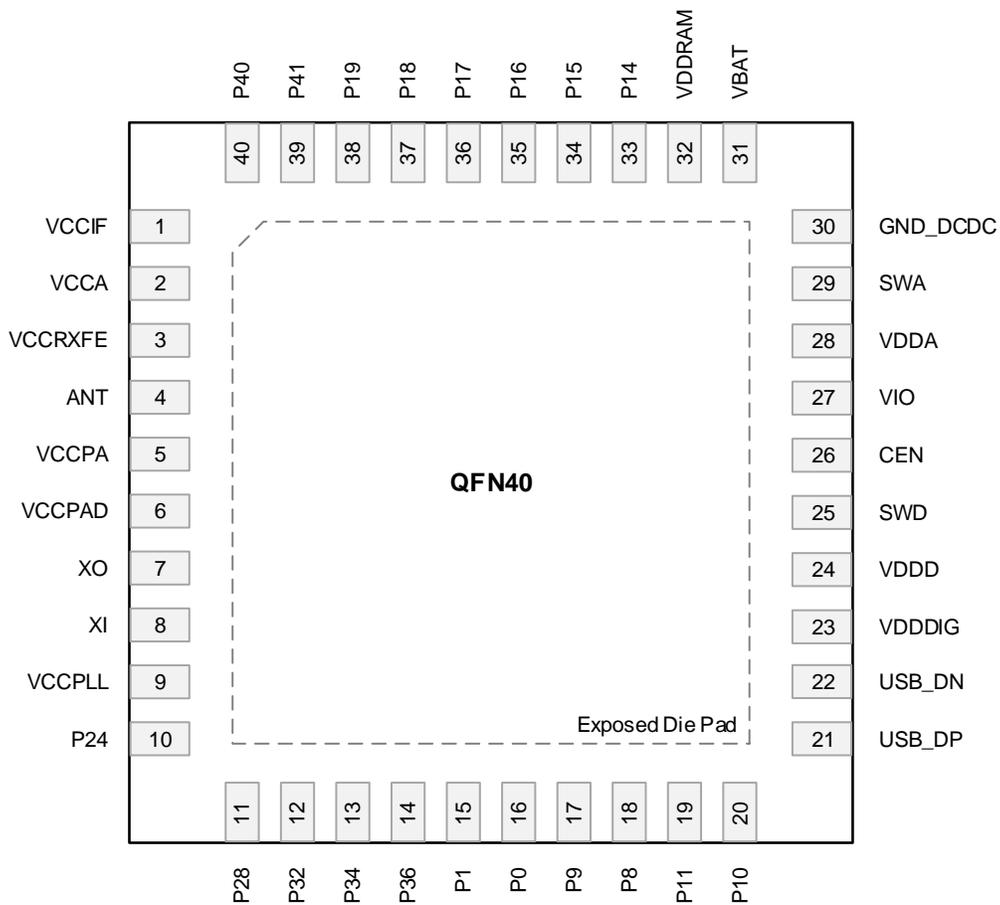


Table 3-1 shows the pin descriptions of the QFN40 package.

Table 3-1 QFN40 Pin Descriptions

Pin #	Name	I/O	Type	Description
1	VCCIF	-	Analog input	IF power supply

Pin #	Name	I/O	Type	Description
2	VCCA	-	Analog input	Analog power supply
3	VCCRFE	-	Analog input	RF receiver power supply
4	ANT	-	RF	2.4 GHz RF signal port
5	VCCPA	-	Analog input	RF PA power supply
6	VCCPAD	-	Analog input	RF PA driver power supply
7	XO	-	Analog output	26 MHz crystal output
8	XI	-	Analog input	26 MHz crystal input
9	VCCPLL	-	Analog input	RF PLL power supply
10	P24	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO24: general-purpose I/O LPO_CLK: 32 kHz clock output PWMG0_PWM4: PWMG0 channel PWM4 ADC2: analog input channel
11	P28	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO28: general-purpose I/O I2S_MCLK: master clock ADC4: analog input channel TOUCH2: touch sensing I/O CLK_AUXS_CIS: CIS master clock (derived from DCO/APLL/CLK_320M/CLK_480M)
12	P32	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO32: general-purpose I/O PWMG1_PWM0: PWMG1 channel PWM0 TOUCH6: touch sensing I/O
13	P34	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO34: general-purpose I/O PWMG1_PWM2: PWMG1 channel PWM2 TOUCH8: touch sensing I/O SPI0_CSN: chip select
14	P36	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO36: general-purpose I/O PWMG1_PWM4: PWMG1 channel PWM4 TOUCH10: touch sensing I/O SPI0_MISO: master in slave out

Pin #	Name	I/O	Type	Description
15	P1	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO1: general-purpose I/O UART1_RX: receive data input I2C1_SDA: serial data SWDIO: serial wire data ADC13: analog input channel LIN_RXD: receive data input
16	P0	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO0: general-purpose I/O UART1_TX: transmit data output I2C1_SCL: serial clock SWCLK: serial wire clock ADC12: analog input channel LIN_TXD: transmit data output
17	P9	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO9: general-purpose I/O PWMG0_PWM3: PWMG0 channel PWM3 DMIC_DAT: data 32K_XI: 32.768 kHz crystal input
18	P8	I/O	Digital/Analog	<ul style="list-style-type: none"> GPIO8: general-purpose I/O PWMG0_PWM2: PWMG0 channel PWM2 DMIC_CLK: clock ADC10: analog input channel 32K_XO: 32.768 kHz crystal output
19	P11	I/O	Digital	<ul style="list-style-type: none"> GPIO11: general-purpose I/O DL_UART_TX: UART flash download transmit data output UART0_TX: transmit data output SDIO_DATA3: data
20	P10	I/O	Digital	<ul style="list-style-type: none"> GPIO10: general-purpose I/O DL_UART_RX: UART flash download receive data input UART0_RX: receive data input SDIO_DATA2: data CLK_AUXS_CIS: CIS master clock (derived from DCO/APLL/CLK_320M/CLK_480M)

Pin #	Name	I/O	Type	Description
21	USB_DP	I/O	Digital	USB D+
22	USB_DN	I/O	Digital	USB D-
23	VDDDIG	-	Analog output	Digital core LDO output
24	VDDD	-	Analog output	Digital buck/LDO output
25	SWD	-	Analog output	Digital buck switch output
26	CEN	-	Analog input	Chip enable, active high
27	VIO	-	Analog output	IO LDO output
28	VDDA	-	Analog output	Analog buck/LDO output
29	SWA	-	Analog output	Analog buck switch output
30	GND_DCDC	-	GND	Buck ground
31	VBAT	-	Power	Chip power supply
32	VDDRAM	-	Analog output	EXMEM LDO output
33	P14	I/O	Digital	<ul style="list-style-type: none"> GPIO14: general-purpose I/O SDIO_CLK: clock SPI0_SCK: serial clock BT_ANT0: Bluetooth antenna select I2C1_SCL: serial clock
34	P15	I/O	Digital	<ul style="list-style-type: none"> GPIO15: general-purpose I/O SDIO_CMD: command/response SPI0_CSN: chip select BT_ANT1: Bluetooth antenna select I2C1_SDA: serial data
35	P16	I/O	Digital	<ul style="list-style-type: none"> GPIO16: general-purpose I/O SDIO_DATA0: data SPI0_MOSI: master out slave in BT_ANT2: Bluetooth antenna select
36	P17	I/O	Digital	<ul style="list-style-type: none"> GPIO17: general-purpose I/O SDIO_DATA1: data SPI0_MISO: master in slave out BT_ANT3: Bluetooth antenna select
37	P18	I/O	Digital	<ul style="list-style-type: none"> GPIO18: general-purpose I/O



Pin #	Name	I/O	Type	Description
				<ul style="list-style-type: none">• SDIO_DATA2: data• PWMG0_PWM0: PWMG0 channel PWM0
38	P19	I/O	Digital	<ul style="list-style-type: none">• GPIO19: general-purpose I/O• SDIO_DATA3: data• PWMG0_PWM1: PWMG0 channel PWM1
39	P41	I/O	Digital	<ul style="list-style-type: none">• GPIO41: general-purpose I/O• UART2_TX: transmit data output• LIN_TXD: transmit data output
40	P40	I/O	Digital	<ul style="list-style-type: none">• GPIO40: general-purpose I/O• UART2_RX: receive data input• LIN_RXD: receive data input
Die pad	GND_SLUG	-	GND	Ground

3.2 Pin Multiplexing

Table 3-2 shows the pin mux functions of GPIOs.

Table 3-2 Pin Multiplexing

GPIO	Flash Download	Alternate Functions						
		AF1	AF2	AF3	AF4	AF5	AF6	AF7
	UART	UART1 UART0 SDIO Clock UART2	I2C1 PWMG0 SDIO SPI0 Clock PWMG1	SWD Clock AoA/AoD AUX ADC LIN	DMIC I2C1 TOUCH	AUX ADC Clock SPI0	LIN	XTALL
GPIO0		UART1_TX	I2C1_SCL	SWCLK		ADC12	LIN_TXD	
GPIO1		UART1_RX	I2C1_SDA	SWDIO		ADC13	LIN_RXD	
GPIO8			PWMG0_PWM2		DMIC_CLK	ADC10		32K_XO
GPIO9			PWMG0_PWM3		DMIC_DAT			32K_XI
GPIO10	DL_UART_RX	UART0_RX	SDIO_DATA2	CLK_AUXS_CIS				
GPIO11	DL_UART_TX	UART0_TX	SDIO_DATA3					
GPIO14		SDIO_CLK	SPI0_SCK	BT_ANT0	I2C1_SCL			
GPIO15		SDIO_CMD	SPI0_CSN	BT_ANT1	I2C1_SDA			
GPIO16		SDIO_DATA0	SPI0_MOSI	BT_ANT2				



	Flash Download	Alternate Functions						
		AF1	AF2	AF3	AF4	AF5	AF6	AF7
GPIO	UART	UART1 UART0 SDIO Clock UART2	I2C1 PWMG0 SDIO SPI0 Clock PWMG1	SWD Clock AoA/AoD AUX ADC LIN	DMIC I2C1 TOUCH	AUX ADC Clock SPI0	LIN	XTALL
GPIO17		SDIO_DATA1	SPI0_MISO	BT_ANT3				
GPIO18		SDIO_DATA2	PWMG0_PWM0					
GPIO19		SDIO_DATA3	PWMG0_PWM1					
GPIO24		LPO_CLK	PWMG0_PWM4	ADC2				
GPIO28			I2S_MCLK	ADC4	TOUCH2	CLK_AUXS_CIS		
GPIO32			PWMG1_PWM0		TOUCH6			
GPIO34			PWMG1_PWM2		TOUCH8	SPI0_CSN		
GPIO36			PWMG1_PWM4		TOUCH10	SPI0_MISO		
GPIO40		UART2_RX		LIN_RXD				
GPIO41		UART2_TX		LIN_TXD				

4. Functional Description

4.1 Wi-Fi/Bluetooth Transceiver

The BK7236M integrates a high-performance Wi-Fi/Bluetooth transceiver. The transceiver incorporates two on-chip baluns. On the receive side, the on-chip balun converts the single-ended (unbalanced) RF signal from the antenna into a differential (balanced) signal and the low noise amplifier (LNA) amplifies the differential signal to achieve a better noise and linearity trade-off. On the transmit side, the power amplifier (PA) amplifies the differential signal and the on-chip balun converts the differential signal to a single-ended signal for feeding the antenna. This enables transmit and receive operations with only one ANT pin connected to the antenna. The frequency synthesizer is fully integrated, eliminating the need for any external components.

4.2 Clock Management

The primary clock sources available in the BK7236M are as follows:

- High-frequency clocks
 - 26 MHz crystal oscillator: it outputs clock signal XTALH
 - 26–360 MHz internal digitally controlled oscillator (DCO): it outputs clock signal CLK_DCO
 - Digital PLL (DPLL): it generates 320 MHz clock CLK_320M and 480 MHz clock CLK_480M
- Low-frequency clocks
 - 32 kHz (32.768 kHz) crystal oscillator: it outputs clock signal XTALL
 - 32 kHz internal ring oscillator (ROSC): it outputs clock signal CLK_ROSC
- Audio clock
 - Audio PLL (APLL): its default frequency is 98.304 MHz, and it outputs clock signal CLK_APLL

The system generates a low-power clock source LPO_CLK for standby. The LPO_CLK can be selected from the following clocks:

- 32 kHz crystal oscillator XTALL
- 32 kHz clock signal derived from 26 MHz crystal oscillator
- 32 kHz internal oscillator ROSC

The BK7236M also has a clock output capability, which allows clock signals to be output to external components through GPIOs. GPIOs can output the following clock signals:

- LPO_CLK: LPO_CLK clock

- I2S_MCLK: reference clock for external audio codec, derived from APLL
- CLK_AUXS_CIS: reference clock for external CMOS image sensor (CIS)

4.3 Reset

A reset can be triggered by the following sources: power-on reset, brown-out reset, watchdog reset, and wake-up from shutdown mode or deep sleep mode.

Power-on reset, brown-out reset, and AWDT watchdog reset reset the whole chip to its initial state. The DWDT watchdog reset's reset scope is configurable and can be configured to reset the whole chip.

Wake-up from shutdown mode triggers the whole system reset, while wake-up from deep sleep mode triggers the reset of digital blocks.

4.4 Power Management

4.4.1 Power Scheme

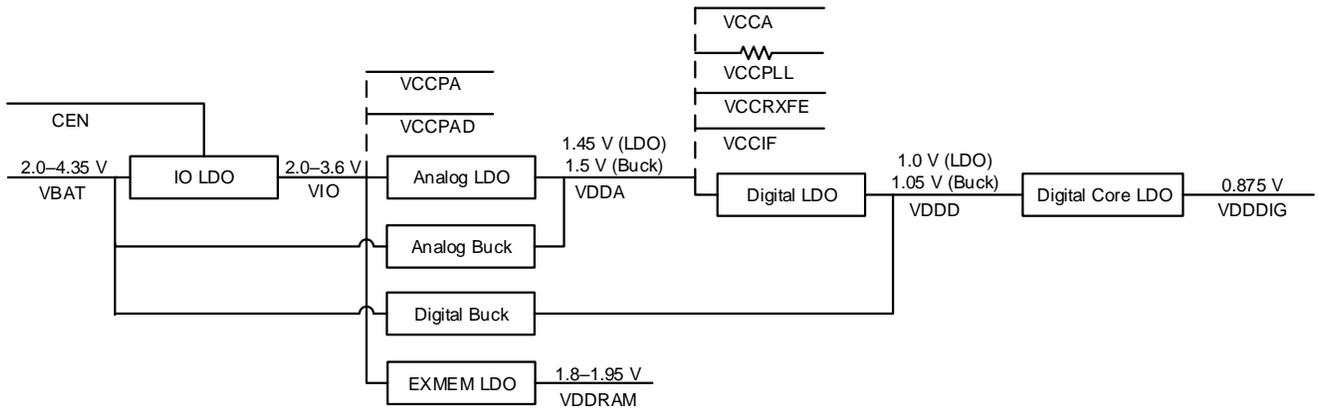
The power management system on the BK7236M includes two buck converters and several internal LDO regulators to provide voltage and noise isolation to various parts of the chip.

The VBAT is the external main chip supply ranging from 2.0 to 4.35 V. The VBAT generates VIO through the IO LDO regulator. In addition to being the power supply for Wi-Fi PA, the VIO is also the input supply of analog LDO, analog buck, digital buck, and EXMEM LDO. The VBAT also generates VDDA and VDDD through the analog buck converter and the digital buck converter, respectively. The LDOs and bucks generate the following main power supplies:

- VDDA: power supply for RF and analog blocks. It is externally connected to VCCA, VCCPLL, VCCRFE, and VCCIF to supply power to Wi-Fi/Bluetooth transceiver, and internally provides power supply to XTAL directly.
- VDDDIG: power supply for digital domain. It provides power supply for the processor, memory, Wi-Fi and Bluetooth basebands, as well as various peripherals.
- VDDRAM: power supply for PSRAM.

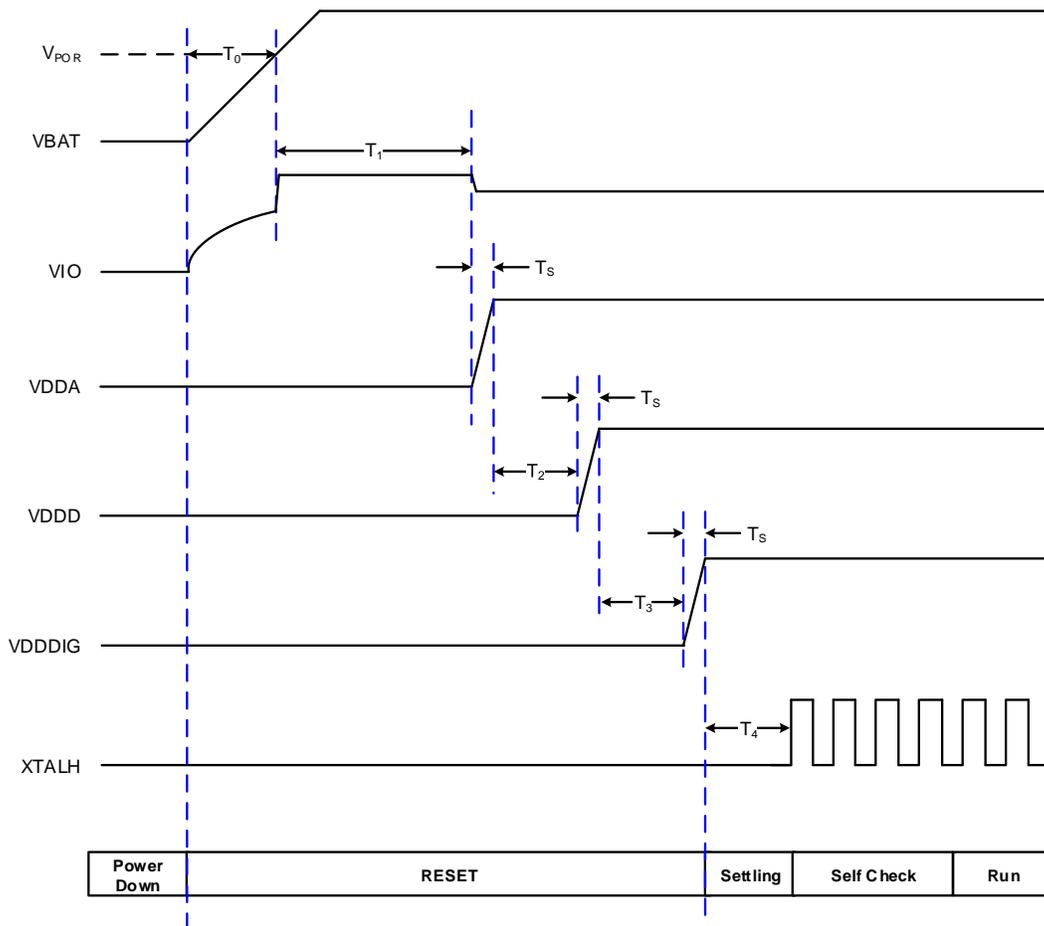
Figure 4-1 shows the power distribution of the BK7236M.

Figure 4-1 Internal Power Distribution



Note: Outputs from the buck converters and LDO regulators require proper bypass capacitors to reduce supply noise. Please refer to the hardware schematic for details on selecting bypass capacitors.

Figure 4-2 shows the power-up sequence of the BK7236M.

Figure 4-2 BK7236M Power-up Sequence

Table 4-1 Timing Parameters of Power-up Sequence

Parameter	Description	Min.	Typ.	Max.	Unit
V _{POR}	VBAT POR threshold	-	1.95	-	V
T ₀	IO LDO settle time	200	-	-	μs
T ₁ ⁽¹⁾	IO LDO ready time	-	-	500	μs
T ₂	Analog buck/LDO ready time	-	240	500	μs
T ₃	Digital buck/LDO ready time	-	240	500	μs
T ₄	Digital core LDO ready time/XTALH stable time	100	-	-	μs
T _s	LDO (excl. IO LDO) settle time	0	-	-	μs

(1) If the VBAT slew rate is greater than 3.3 kV/s, VIO will overshoot.

Figure 4-3 shows the power-down sequence of BK7236M.

Figure 4-3 BK7236M Power-down Sequence

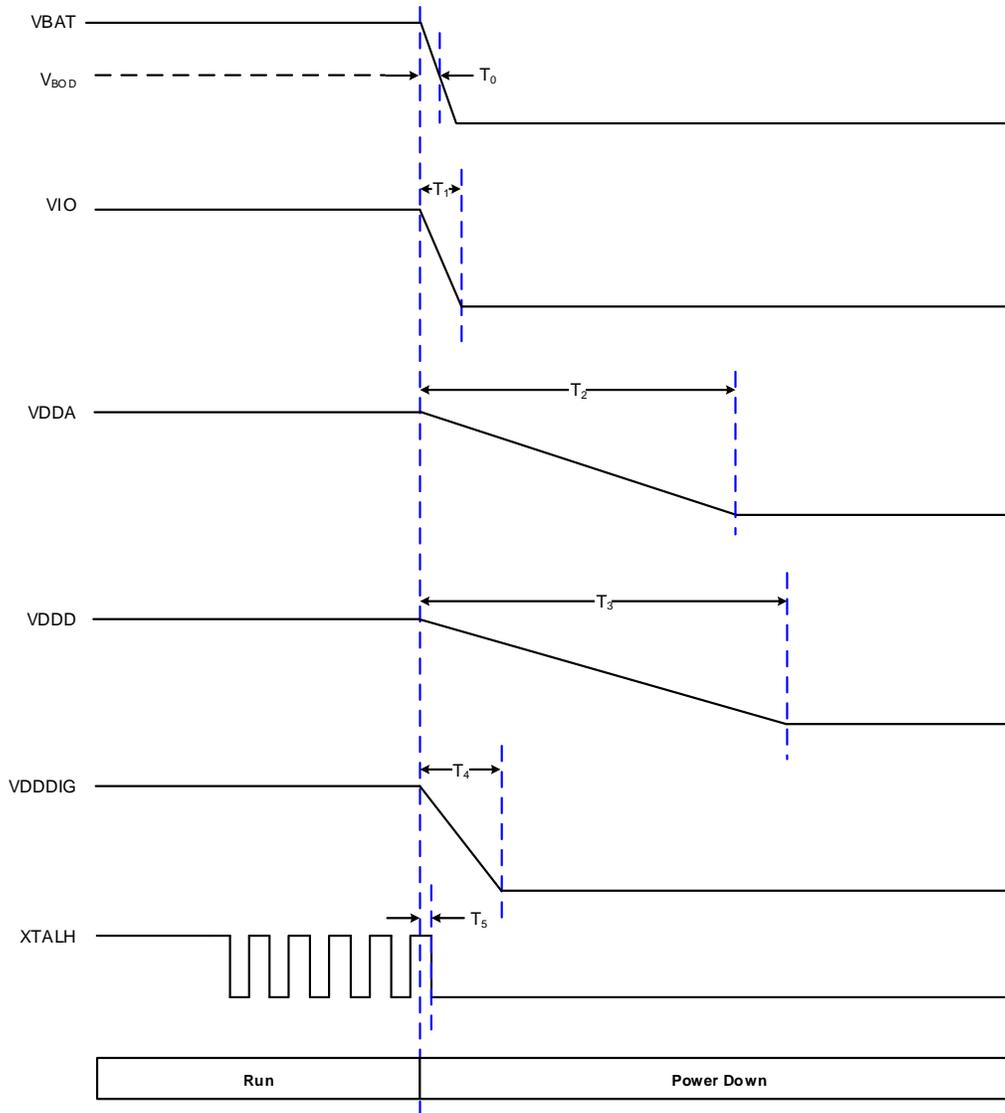


Table 4-2 Timing Parameters of Power-down Sequence

Parameter	Description	Min.	Typ.	Max.	Unit
V_{BOD}	VBAT BOD threshold	-	1.85	-	V
T_0	VBAT power-down time	-	400	-	μ s
T_1	IO LDO power-down time	-	600	-	μ s
T_2	Analog buck/LDO power-down time	-	400	-	ms

Parameter	Description	Min.	Typ.	Max.	Unit
T ₃	Digital buck/LDO power-down time	-	500	-	ms
T ₄	Digital core LDO power-down time	-	3.5	-	ms
T ₅	XTALH power-down time	-	100	-	μs

4.4.2 Power Modes

The BK7236M supports three low-power modes except active mode, namely shutdown mode, deep sleep mode, and sleep mode, among which the shutdown mode has the lowest power consumption.

Shutdown Mode: All circuits are turned off. A high level on the CEN pin will bring the system to active mode.

Deep Sleep Mode: All circuits are powered down except the AON block. GPIOs, RTC, or touch sensing I/O pins can power up the system again. The retention register holds its content.

Sleep Mode: The MCU and all digital blocks stop their clocks. GPIOs, RTC, touch sensing I/O pins, or Wi-Fi/Bluetooth MAC low-power counters can bring the system back to active mode with normal voltage.

Active Mode: The MCU is active, and all peripherals are available.

4.5 General-purpose I/Os (GPIO)

The BK7236M has up to 19 GPIOs, which can be configured as either input or output. All GPIOs are shared with alternate functions. Table 3-2 Pin Multiplexing provides the mux functions of GPIOs.

The main features of GPIOs include:

- Push-pull
- Internal pull-up/down resistors
- Configurable drive strength
- Alternate function
- Interrupt generation:
 - High or low level
 - Rising or falling edge

4.6 SPI Interface (SPI)

The BK7236M integrates an SPI interface that can operate in master or slave mode. The SPI interface allows a clock frequency up to 40 MHz in both master and slave modes.

The SPI interface supports the following features:

- 4-wire or 3-wire full-duplex synchronous communication
- Configurable 8-bit or 16-bit data width
- Programmable clock polarity and phase
- Programmable data order with MSB-first or LSB-first shifting
- Embedded 64-depth RX FIFO and 64-depth TX FIFO with DMA capability

4.7 UART Interfaces (UART)

The BK7236M includes three Universal Asynchronous Receiver/Transmitter (UART) interfaces, which support full-duplex, asynchronous serial communication at a baud rate up to 6 Mbps.

The UART interfaces offer the features below:

- Configurable data length (5, 6, 7, or 8 bit)
- Even, odd, or none parity check
- Programmable stop bits (1 or 2 bits)
- Each UART embeds a 128-byte TX FIFO and a 128-byte RX FIFO. FIFO mode is disabled by default and can be enabled by software.
- Flash download (UART0)
- Programmable digital filter

4.8 SDIO Interface (SDIO)

A secure digital input/output (SDIO) host/slave interface is available on the BK7236M. It can be used as a host to read external SD cards or used by an external host as a slave to communicate with chips. The SDIO interface allows a maximum clock speed of 80 MHz.

The SDIO features include the following:

- SD memory card specification version 2.0 compliant
- SDIO card specification version 2.0 compliant
- Two data bus modes: 1-bit mode (default) and 4-bit mode
- Data transfer up to 40 Mbyte/s for the host mode and 20 Mbyte/s for the slave mode
- Supports DMA capability, allowing high-speed transfer without CPU load

4.9 I2C Interface (I2C)

I2C is a popular inter-IC interface that requires only two bus lines, the serial data line (SDA) and the serial clock line (SCL). The BK7236M embeds an I2C interface, which can operate in master or slave mode.

The features of the I2C interface are listed below:

- Master and slave modes
- Standard mode (up to 100 kbps)
- Fast mode (up to 400 kbps)
- 7-bit and 10-bit addressing
- Bus idle and SCL low timeout condition detection
- Embedded 16-byte TX FIFO and 16-byte RX FIFO

4.10 USB Controller (USB)

The BK7236M embeds a USB high-speed (up to 480 Mbps) controller with an integrated transceiver. It can operate as a host or a device.

The USB controller features are the following:

- Compliant with the Universal Serial Bus Specification Rev 1.1 and 2.0
- Full-speed (FS) operation (up to 12 Mbps) and high-speed operation (up to 480 Mbps)
- One bidirectional control endpoint0
- Seven IN/OUT endpoints configurable to support bulk, interrupt or isochronous data transfer
- A FIFO of 8 Kbytes configurable to be allocated to 8 endpoints
- USB 2.0 Link Power Management (LPM) support

4.11 LIN Controller (LIN)

The Local Interconnect Network (LIN) controller is a communication controller that performs serial communication. It implements the data link layer of the LIN Protocol Specification. The LIN protocol uses a single master/multiple slave concept for the frame transfer between nodes of the LIN network.

The features of the LIN controller are listed here:

- Support of LIN specification 2.2A
- Backward compatibility to LIN 1.3
- Configurable for support of master or slave functionality

- Programmable data rate between 1 kbit/s and 20 kbit/s (for master)
- Automatic bit rate detection (for slave)
- 8-byte data buffer
- 8-bit host controller interface

4.12 GDMA Controllers (GDMA)

The BK7236M has two general-purpose DMA controllers (GDMA) with 8 DMA channels each to unload CPU activity. The 8 channels are shared by peripherals that have DMA capabilities.

The GDMA controllers can perform single block transfers and repeated block transfers. Data width for destination and source can be configured as 8 bits (byte), 16 bits (half-word), or 32 bits (word). The GDMA controllers allow peripheral to memory, memory to memory, and memory to peripheral data transfers at a high speed.

The GDMA controllers support channel isolation. The DMA channels can be configured as secure/non-secure and as privileged/unprivileged channels:

- A non-secure channel performs non-secure DMA transfers
- A secure channel can perform secure or non-secure DMA transfers, with
 - Secure or non-secure data read from the source address
 - Secure or non-secure data write to the destination address
 - Via a TrustZone-aware DMA AHB master port
- An unprivileged channel performs unprivileged DMA transfers
- A privileged channel performs privileged DMA transfers

A selection of peripherals on the BK7236M have DMA capabilities, including UART0, UART1, UART2, SPI0, SDIO, AUX ADC, and DMIC.

4.13 PWM Groups (PWMG)

The BK7236M has two advanced-control PWM groups (PWMG). Each PWMG consists of up to four independent 32-bit auto-reload counters driven by four programmable prescalers. The PWMGs can generate pulse width modulated signals for a variety of purposes, including input capture, pulse edge counting, or generation of output waveforms (output compare).

The features of one PWMG are listed here:

- Up to four 32-bit up, down, or up-and-down auto-reload counters
 - PWM0 has a counter.
 - PWM1 has a counter (up-counting mode only).

- PWM2 and PWM3 share a counter.
- PWM4 has a counter.
- Up to four 8-bit programmable prescalers capable of dividing the clock frequency of each counter by any factor between 1 and 256
- PWMG0 has four independent channels and PWMG1 has three independent channels, among which:
 - PWM0/2/4
 - Input capture
 - Pulse edge counting
 - PWM generation (edge or center-aligned mode)
 - PWM1
 - Independent simple waveform generation (up-counting mode)
 - Coupled waveform (reverse or identical) generation when coupled with PWM0
- Complementary outputs with programmable dead-time and configurable dead-time mode
- Synchronization circuit to control the counter with external signals and to interconnect several counters together
- Repetition counter to update the registers only after a given number of cycles of the counter
- Interrupt generation on the following events:
 - Update: counter overflow or underflow, counter initialization (by software or internal/external trigger)
 - Counter start
 - Input capture
 - Output compare
- Change of polarity, duty cycle, and base frequency on every PWM period
- Supports incremental (quadrature) encoder and Hall-sensor circuitry for positioning purposes

Table 4-3 below provides the description of PWM signals.

Table 4-3 PWM Signals

GPIO	PWM Pin Name	Signal Type	Description
PWMG0			
GPIO18	PWMG0_PWM0	I/O	PWMG0 channel PWM0
GPIO19	PWMG0_PWM1	I/O	PWMG0 channel PWM1 PWM1 can work independently to generate simple waveforms or couple with PWM0 (with deadtime insertion) to generate reverse or identical waveforms of PWM0.

GPIO	PWM Pin Name	Signal Type	Description
GPIO8 ⁽¹⁾	PWMG0_PWM2	I/O	PWMG0 channel PWM2 ⁽²⁾
GPIO9	PWMG0_PWM3	I/O	PWMG0 channel PWM3 ⁽²⁾ PWM3 can couple with PWM2 (with deadtime insertion) to generate reverse or identical waveforms of PWM2.
GPIO24	PWMG0_PWM4	I/O	PWMG0 channel PWM4
PWMG1			
GPIO32	PWMG1_PWM0	I/O	PWMG1 channel PWM0
GPIO34	PWMG1_PWM2	I/O	PWMG1 channel PWM2
GPIO36	PWMG1_PWM4	I/O	PWMG1 channel PWM4

(1) It is not recommended to use GPIO8 for LED and motor control.

(2) When PWM2 and PWM3 are enabled simultaneously, they cannot generate waveforms with different duty cycles.

4.14 Digital Microphone Interface (DMIC)

The BK7236M has a digital microphone interface that supports two digital microphones. The PDM performs 8:1 CIC decimation, and the PCM sampling rate can be up to 384 kHz when the PDM clock frequency is 3.072 MHz.

4.15 Auxiliary ADC (AUX ADC)

The auxiliary ADC (AUX ADC) is a 12-bit successive approximation analog-to-digital converter. The AUX ADC has multiple external analog input channels and internal dedicated channels. The AUX ADC supports A/D conversion performed in one-shot, software control, or continuous mode.

The AUX ADC module has the following features:

- Programmable sampling rate from 12.5 to 812.5 kHz
- 12-bit resolution
- Up to five external analog input channels: ADC2/4/10/12/13
- Five internal dedicated channels:
 - VBAT monitoring channel (VBAT/2, VBAT/3, VBAT/5, or VBAT/7), connected to ADC0
 - Internal temperature sensor (TEMP), connected to ADC7
 - TSSIO, connected to ADC8
 - Touch OUT_TD, connected to ADC9
 - Internal debug channel, connected to ADC11

- Conversion modes:
 - One-shot mode
 - Software control mode
 - Continuous mode

4.16 Timer Groups (TIMG)

The BK7236M includes two general-purpose timer groups (TIMG). Each group has three 32-bit timers. Each group consists of three 32-bit counters driven by a 4-bit prescaler.

Each TIMG module has the following features:

- Three timers (Timer0/1/2)
- Three 32-bit up counters
- 4-bit prescaler, factor between 1 and 16
- Capable of reading the real-time value of the counter

4.17 Watchdog Timers (WDT)

The BK7236M has two watchdog timers, the digital power domain watchdog timer (DWDT) and the AON power domain watchdog timer (AWDT). The purpose of the watchdog timers is to detect and recover from failures or malfunctions. The watchdog timers trigger a reset on expiry of a specified time period.

The DWDT runs on the 32 kHz LPO_CLK clock (factor 2/4/8/16) and has a maximum programmable period of up to 32.768 ($2^{16}/2$ kHz) seconds. The AWDT runs on the ROOSC and has a maximum programmable period of up to 65.536 ($2^{16}/1$ kHz) seconds.

4.18 Real-time Counter (RTC)

The real-time counter (RTC) module features a 64-bit counter and a tick event generator. The RTC runs on the 32 kHz LPO_CLK clock. It is used for low-power timing, and it can keep running even when the system is in deep sleep mode.

4.19 Temperature Sensor

The BK7236M integrates an on-chip temperature sensor that can measure on-chip temperature over -40 to +125 °C with an accuracy of ± 5 °C. The digital results can be read from the AUX ADC.

Usually, the software initiates the calibration of a specific module based on the temperature value, narrowing the difference in chip performance at different temperatures. The host can also read the on-chip temperature and decide whether to reduce transmit power or suspend operation at high temperatures.

4.20 Touch Sensor (TOUCH)

The BK7236M has four capacitive sensing I/Os, which immediately detect capacitance changes induced by touch or proximity of objects.

4.21 Security

The BK7236M provides state-of-the-art security based on a powerful security architecture. It integrates a total security solution for Internet of Things (IoT), IoT Platform Security Suite (IPSS). The IPSS aims to set up a top-secret execution environment for IoT devices. With the state-of-the-art security technology, it is intended for power/cost/resource sensitive IoT market applications.

The IPSS introduces a fundamental software IP solution for cryptograph and system security control. The key features of the IPSS include:

- Secure boot
- Secure debug
- Secure connection
- Firmware Over-The-Air (FOTA)
- Provisioning
- TEE_M
- TrustEngine

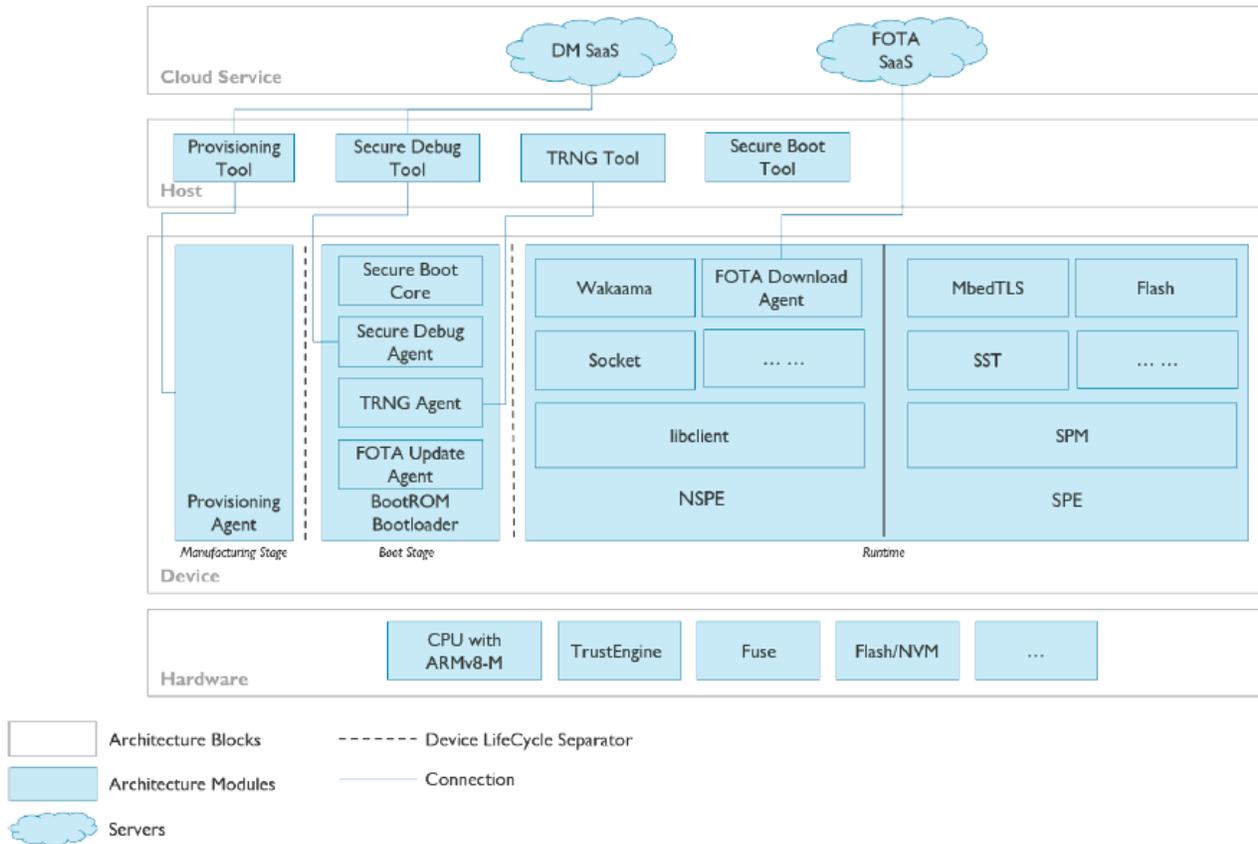
System Architecture

The IPSS software implements an all-round device-to-cloud security architecture, including:

- Provisioning mechanism in the manufacturing stage.
- Secure boot, secure debug, TRNG calibration, and FOTA update in the device boot stage.
- Secure connection and FOTA download in the device run-time stage.

IPSS also introduces a remote management solution to enable users to access, monitor and manage IoT devices in a secure manner. The remote management solution includes FOTA SaaS, Secure Debug SaaS, and Provisioning SaaS.

The following figure shows the architecture of the IPSS system.

Figure 4-4 Security Architecture of the IPSS System


4.21.1 Secure Boot

The secure boot solution provides the legitimacy and trustworthiness for images running on devices. It ensures that only official images which are published from OEMs are executable.

The secure boot functions include following aspects:

- Image verification
- Image encryption
- Extended program execution
- Image anti-rollback protection

4.21.2 Secure Debug

Secure debug provides a reliable mechanism for enabling the debug feature of a device after the device deployment.

Debug is one of the most commonly-used features in the device. With the debug feature, you can access all the device data, including the device firmware and the device root key.

4.21.3 FOTA

The FOTA solution implements a series of light-weight and trustworthy firmware upgrade interaction between IoT devices and servers, which includes downloading, verification, and installation.

4.21.4 Provisioning

Provisioning is the process to initialize secure credentials onto devices. It is required to happen in a secure environment such as the product line in the manufacturing stage.

The provisioning solution provides a full secure mechanism from the cloud server to devices. It keeps the security and integrity of provisioning materials, such as the device ID, model key, and the secure boot/secure debug public key hash, also keeps the device top secret such as the device root key that occurs only on the device side.

4.21.5 Secure Connection

The secure connection feature uses Mbed TLS to provide connection security in the transport layer over UDP. The key exchange method is Pre-Shared Key (PSK). The PSK's deployment happens in the manufacturing stage.

Mbed TLS provides cryptograph and SSL/TLS capabilities with TLS 1.1 and TLS 1.2.

4.21.6 BootROM

IPSS includes the BootROM reference code which is integrated with the secure boot solution.

There are primary boot and recovery boot paths in the BootROM.

- Primary boot is the main boot path. Normally devices should boot to the primary path.
- Recovery boot is the secondary boot path.

4.21.7 Bootloader

IPSS includes the Bootloader reference code which is integrated with the secure debug, provisioning, TRNG calibration, and FOTA solution.

In the primary bootloader, the secure debug agent, provisioning agent, and TRNG agent are integrated. The primary bootloader boots to the next image—TEE_M.

In the recovery bootloader, both the secure debug agent, TRNG agent, and the FOTA update agent are integrated. The recovery bootloader does not boot to any images.

4.21.8 TEE_M

IPSS introduces TEE_M. TEE_M provides an implementation of secure world software for Armv8-M, which follows Arm Platform Security Architecture (PSA) PSA_Firmware_Framework_1.0-beta0. IPSS TEE_M provides the following services by default:

- Secure Storage: The Secure Storage (Only supports Protected Storage) service supports PSA_Storage_API-1.0-beta2 without extended functions.
- Crypto: The Crypto service supports PSA_Cryptography_API_Reference_1.0_beta1.
- DTLS: DTLS (leverages Mbed TLS) is integrated in TEE_M.

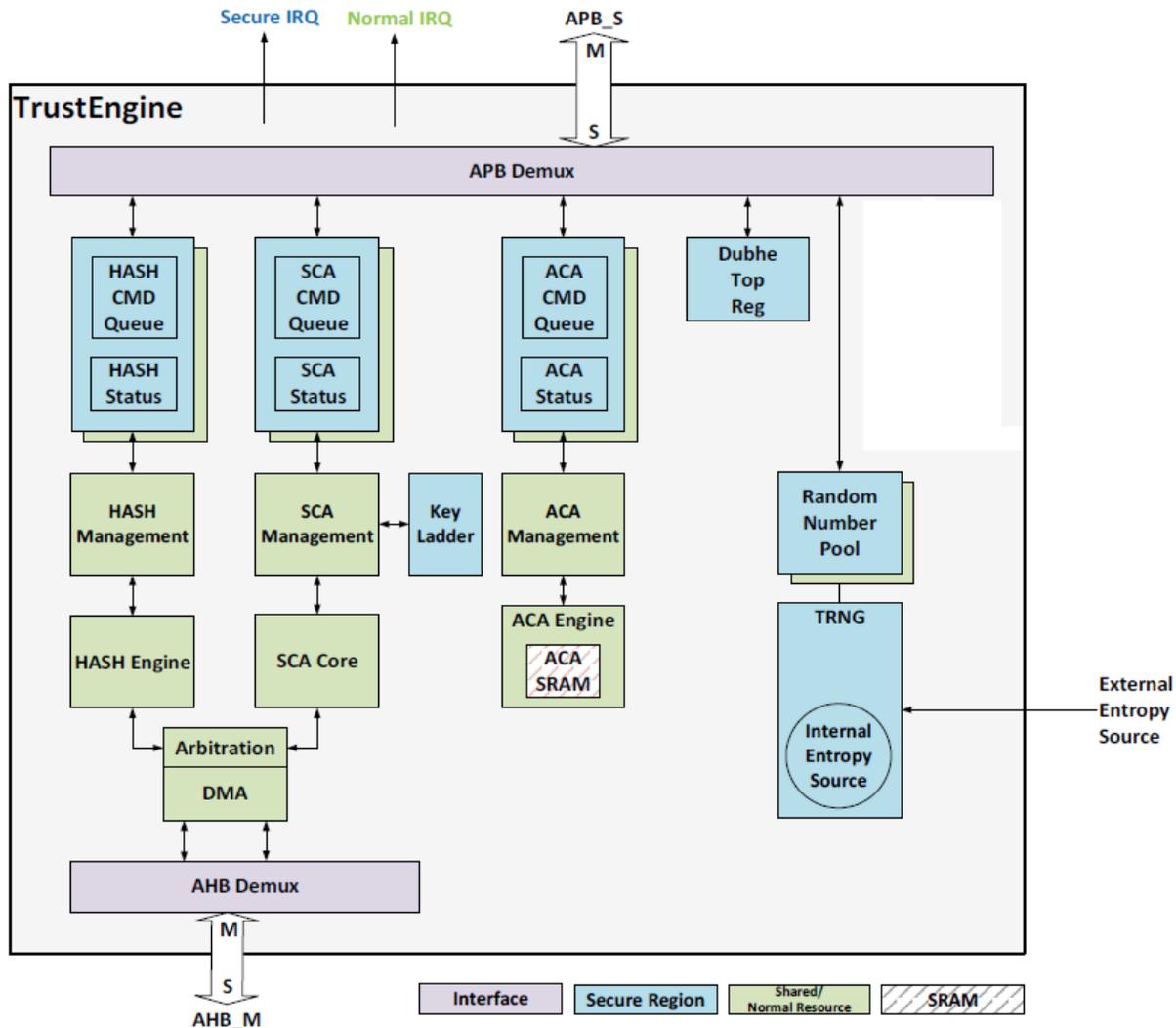
4.21.9 TrustEngine

IPSS introduces TrustEngine as a secure component in the system. It provides the following features:

- High security assurance. The crypto engine supports key ladders, lifecycle management and True Random Number Generator (TRNG) which enhance the system security.
- High performance and low power for encryption/decryption operation. This is achieved by TrustEngine internal cryptography engines.
- Reduction of software complicity in security. Some security functions are implemented in TrustEngine hardware, which can reduce the risk of sensitive information leakage to non-secure hosts.

The following figure shows the TrustEngine top-level architecture.

Figure 4-5 TrustEngine Top-Level Architecture



4.21.9.1 Features

TrustEngine includes the following features:

- Symmetric schemes, AES-ECB/CBC/CTR/CBC-MAC/CMAC/CCM/GCM (key size 128-bit, 192-bit and 256-bit)
- Symmetric schemes, SM4-ECB/CBC/CTR/CBC-MAC/CMAC/CCM/GCM
- Digest schemes, SHA1/224/256
- Digest scheme, SM3
- Asymmetric schemes, RSA 1024/2048/3072/4096 and ECCP 192/224/256/384/512/521
- Asymmetric scheme, SM2
- Key ladder for key management

- Lifecycle management
- True random number generator

4.21.9.2 Supported Standards and Specifications

TrustEngine is compliant with the following standards:

- FIPS PUB 180-4: Secure Hash Standard (SHS)
- FIPS PUB 197: Advanced Encryption Standard (AES)
- NIST SP 800-38A Recommendation for Block Cipher Modes of Operation-Methods and Techniques
- NIST SP 800-38B Recommendation for Block Cipher Modes of Operation: The CMAC Mode for Authentication
- NIST SP 800-38C Recommendation for Block Cipher Modes of Operation-the CCM Mode for Authentication and Confidentiality
- NIST SP 800-38D, Recommendation for Block Cipher Modes of Operation: Galois/Counter Mode (GCM) and GMAC
- NIST SP 800-90B Recommendation for the Entropy Sources Used for Random Bit Generation
- SM2 Public Key Cryptographic Algorithm Based on Elliptic Curves (GB/T 32918-2016)
- SM3 Cryptographic Hash Algorithm (GB/T 32905-2016)
- SM4 Block Cipher Algorithm (GB/T 32907-2016)

4.21.9.3 Components

TrustEngine consists of five major function blocks.

- Symmetric Cryptography Accelerator (SCA)
- Asymmetric Cryptography Accelerator (ACA)
- HASH engine
- One-time programmable storage access controller
- True random number generator

Symmetric Cryptography Accelerator (SCA)

SCA in TrustEngine is responsible for data encryption/decryption using the symmetric cryptography algorithm. The data encryption/decryption operations are performed through the SCA engine by sending special commands to TrustEngine.

Asymmetric Cryptography Accelerator (ACA)

The ACA engine in TrustEngine is responsible for accelerating the asymmetric cryptography, such as:

- Asymmetric encryption and decryption: RSA and ECC
- Digital signature and verification: RSA signatures and ECDSA
- Key exchange: DH (Diffie-Hellman) and ECDH



HASH Accelerator

The HASH engine in TrustEngine is responsible for digest calculation. The digest of certain data can be calculated through the HASH engine by sending special commands to TrustEngine.

True Random Number Generator

The True Random Number Generator (TRNG) generates the random bits using the internal entropy source (ring oscillator inverter chain) or the external entropy source. The random bits are required by both secure and non-secure hosts.

5. Electrical Characteristics

5.1 Absolute Maximum Ratings

Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. Exposure to absolute-maximum-rated conditions for prolonged periods may affect the reliability of the device.

Parameter	Description	Min.	Max.	Unit
V _{BAT}	Chip power supply voltage	-0.3	4.5	V
V _{IO}	IO LDO output voltage	-0.3	4.0	V
V _{CCPA}	Supply voltage for PA	-0.3	4.0	V
V _{CCPAD}	Supply voltage for PA driver	-0.3	4.0	V
V _{CCIF}	Supply voltage for IF	-0.3	1.8	V
V _{CCR_{XFE}}	Supply voltage for RX	-0.3	1.8	V
V _{CCPLL}	Supply voltage for RF PLL	-0.3	1.8	V
V _{CCA}	Supply voltage for analog	-0.3	1.8	V
V _{DDA}	Analog buck/LDO output voltage	-0.3	1.8	V
V _{DDD}	Digital buck/LDO output voltage	-0.3	1.2	V
V _{DDDIG}	Digital core LDO output voltage	-0.3	1.1	V
V _{DDRAM}	EXMEM LDO output voltage	-0.3	2.1	V
SW _A	Analog buck switch output voltage	-0.3	4.5	V
SW _D	Digital buck switch output voltage	-0.3	4.5	V
P _{RX}	RX input power	-	10	dBm
T _{STR}	Storage temperature range	-55	150	°C

5.2 ESD Ratings

Parameter	Description	Test Condition	Value	Unit
ESD HBM	Electrostatic discharge voltage (human body model), per ANSI/ESDA/JEDEC JS-001	-	±2000	V

Parameter	Description	Test Condition	Value	Unit
ESD CDM	Electrostatic discharge voltage (charge device model), per ANSI/ESDA/JEDEC JS-002	-	±500	V

5.3 Recommended Operating Conditions

Parameter	Description	Min. ⁽¹⁾	Typ.	Max.	Unit
VBAT ⁽²⁾	Chip power supply voltage	2.0	3.3	4.35	V
VBAT slew rate	-	300	-	-	mV/ms
VIO	IO LDO output voltage	2.0	-	3.6	V
VCCPA ⁽²⁾	Supply voltage for PA	2.0	-	3.6	V
VCCPAD ⁽²⁾	Supply voltage for PA driver	2.0	-	3.6	V
VCCIF	Supply voltage for IF	-	1.45	-	V
VCCRxFE	Supply voltage for RX	-	1.45	-	V
VCCPLL	Supply voltage for RF PLL	-	1.45	-	V
VCCA	Supply voltage for analog	-	1.45	-	V
VDDA	Analog LDO output voltage	-	1.45	-	V
	Analog buck output voltage	-	1.5	-	V
VDDD	Digital LDO output voltage	-	1.0	-	V
	Digital buck output voltage	-	1.05	-	V
VDDDIG	Digital core LDO output voltage	-	0.875	-	V
VDDRAM	EXMEM LDO output voltage	1.8	-	1.95	V
T _{OPR}	Operating temperature range	-40	-	105	°C

(1) The minimum voltage specified includes the ripple on the supply voltage and all other transient dips. Care must be taken when operating at the minimum specified voltage.

(2) To ensure WLAN performance, the ripple on the supply must be less than $V_{pp} = 100$ mV.

5.4 Digital I/O Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
VIH	High-level input voltage	-	0.7 VIO	-	VIO + 0.3	V

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
VIL	Low-level input voltage	-	-0.3	-	0.3 V _{IO}	V
VOH	High-level output voltage	-	0.9 V _{IO}	-	-	V
VOL	Low-level output voltage	-	-	-	0.1 V _{IO}	V
I _{DRV}	I/O output drive strength	-	5	-	20	mA
R _{PU}	Weak pull-up resistor	-	-	40	-	kΩ
R _{PD}	Weak pull-down resistor	-	-	44	-	kΩ

5.5 IO LDO

Parameter	Description	Min.	Typ.	Max.	Unit
V _{IO}	IO LDO output voltage	2.0	3.3	3.6	V
Load current	-	-	-	500	mA

5.6 Analog LDO

Parameter	Description	Min.	Typ.	Max.	Unit
V _{DDA}	Analog LDO output voltage	-	1.45	-	V
Load current	-	-	-	150	mA

5.7 Digital LDO

Parameter	Description	Min.	Typ.	Max.	Unit
V _{DDD}	Digital LDO output voltage	-	1.0	-	V
Load current	-	-	-	100	mA

5.8 Core LDO

Parameter	Description	Min.	Typ.	Max.	Unit
V _{DDDIG}	Digital core LDO output voltage	-	0.875	-	V
Load current	-	-	-	100	mA

5.9 Analog Buck

Parameter	Description	Min.	Typ.	Max.	Unit
VDDA	Analog buck output voltage	-	1.5	-	V
Load current	-	-	-	150	mA
Switching frequency	Buck modulation frequency	0.5	1	2	MHz
Output filter capacitor capacitance	-	-	4.7	-	μF
Inductor inductance	-	-	4.7	-	μH
Inductor DC resistance	-	-	-	500	$\text{m}\Omega$
Inductor saturation current	-	200	-	-	mA

5.10 Digital Buck

Parameter	Description	Min.	Typ.	Max.	Unit
VDDD	Digital buck output voltage	-	1.05	-	V
Load current	-	-	-	100	mA
Switching frequency	Buck modulation frequency	0.5	1	2	MHz
Output filter capacitor capacitance	-	-	4.7	-	μF
Inductor inductance	-	-	4.7	-	μH
Inductor DC resistance	-	-	-	500	$\text{m}\Omega$
Inductor saturation current	-	200	-	-	mA

5.11 26 MHz Crystal Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
F0	Nominal frequency	-	-	26	-	MHz
$\Delta\text{F}/\text{F0}$	Frequency tolerance	25 °C	-10	-	+10	ppm
TC	Frequency stability over operating temperature	-40 to 105 °C crystal	-20	-	+20	ppm
		-30 to 85 °C crystal	-10	-	+10	ppm

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
CL	Load capacitance	-	7	7.3	12	pF
TS	Trim sensitivity	-40 to 105 °C crystal	-	32	-	ppm/pF
		-30 to 85 °C crystal	-	17	-	ppm/pF

5.12 Current Consumption

Measured with T = 25 °C, VBAT = 3.3 V unless otherwise stated.

Parameter	Condition	Min.	Typ.	Max.	Unit
Active Mode					
RX current	11b: 11 Mbps DSSS	-	17.5	-	mA
	11g: 54 Mbps OFDM	-	17.5	-	mA
	11n: MCS7, HT20	-	17.5	-	mA
	11n: MCS7, HT40	-	18.5	-	mA
	11ax: MCS7, HE20	-	17.5	-	mA
TX current	11b: 11 Mbps DSSS @ 19 dBm	-	235	-	mA
	11g: 54 Mbps OFDM @ 17 dBm	-	200	-	mA
	11n: MCS7, HT20 @ 16 dBm	-	189	-	mA
	11n: MCS7, HT40 @ 15 dBm	-	182	-	mA
	11ax: MCS7, HE20 @ 16 dBm	-	188	-	mA
Sleep Mode					
Sleep	-	-	43	-	μA
Deep sleep	-	-	16	-	μA
Shutdown Mode					
Shutdown	-	-	2.5	-	μA

5.13 WLAN RF Receiver Characteristics

Measured with T = 25 °C, VBAT = 3.3 V unless otherwise stated.

Parameter	Condition	Min.	Typ.	Max.	Unit
General					
Frequency range	-	2412	-	2484	MHz
Sensitivity					
Sensitivity - IEEE 802.11b (8% PER for 1024 octet PSDU)	1 Mbps DSSS	-	-98	-	dBm
	2 Mbps DSSS	-	-94.5	-	dBm
	5.5 Mbps DSSS	-	-92	-	dBm
	11 Mbps DSSS	-	-89	-	dBm
Sensitivity - IEEE 802.11g (10% PER for 1000 octet PSDU)	6 Mbps OFDM	-	-92	-	dBm
	9 Mbps OFDM	-	-91.5	-	dBm
	12 Mbps OFDM	-	-90.5	-	dBm
	18 Mbps OFDM	-	-88	-	dBm
	24 Mbps OFDM	-	-85	-	dBm
	36 Mbps OFDM	-	-82	-	dBm
	48 Mbps OFDM	-	-77.5	-	dBm
	54 Mbps OFDM	-	-76.5	-	dBm
Sensitivity - IEEE 802.11n, 20 MHz (10% PER for 4096 octet PSDU, LDPC)	HT20, MCS0	-	-92	-	dBm
	HT20, MCS1	-	-91	-	dBm
	HT20, MCS2	-	-88	-	dBm
	HT20, MCS3	-	-86	-	dBm
	HT20, MCS4	-	-82	-	dBm
	HT20, MCS5	-	-78	-	dBm
	HT20, MCS6	-	-76.5	-	dBm
	HT20, MCS7	-	-75	-	dBm
Sensitivity - IEEE 802.11n, 40 MHz (10% PER for 4096 octet PSDU,	HT40, MCS0	-	-87.5	-	dBm
	HT40, MCS1	-	-87	-	dBm



Parameter	Condition	Min.	Typ.	Max.	Unit
LDPC)	HT40, MCS2	-	-85	-	dBm
	HT40, MCS3	-	-82.5	-	dBm
	HT40, MCS4	-	-79	-	dBm
	HT40, MCS5	-	-75	-	dBm
	HT40, MCS6	-	-74	-	dBm
	HT40, MCS7	-	-71.5	-	dBm
Sensitivity - IEEE 802.11ax, 20 MHz (10% PER for 4096 octet PSDU, LDPC)	HE20, MCS0	-	-92	-	dBm
	HE20, MCS1	-	-90.5	-	dBm
	HE20, MCS2	-	-87.5	-	dBm
	HE20, MCS3	-	-85	-	dBm
	HE20, MCS4	-	-81	-	dBm
	HE20, MCS5	-	-77.5	-	dBm
	HE20, MCS6	-	-75.5	-	dBm
	HE20, MCS7	-	-74	-	dBm
Sensitivity - IEEE 802.11ax, 40 MHz (10% PER for 4096 octet PSDU, LDPC)	HE40, MCS0	-	-88.5	-	dBm
	HE40, MCS1	-	-87.5	-	dBm
	HE40, MCS2	-	-85.5	-	dBm
	HE40, MCS3	-	-82	-	dBm
	HE40, MCS4	-	-77	-	dBm
	HE40, MCS5	-	-75	-	dBm
	HE40, MCS6	-	-74	-	dBm
	HE40, MCS7	-	-72	-	dBm
Maximum Receive Level					
Maximum receive level @ 2.4 GHz	11b: 1, 2 Mbps (8% PER, 1024 octets)	-	10	-	dBm
	11b: 5.5, 11 Mbps (8% PER, 1024 octets)	-	10	-	dBm
	11g: 6–54 Mbps (10% PER, 1000 octets)	-	0	-	dBm

Parameter	Condition	Min.	Typ.	Max.	Unit	
	11n: MCS0–7 (10% PER, 4096 octets)	-	0	-	dBm	
	11ax: MCS0–7 (10% PER, 4096 octets)	-	0	-	dBm	
Adjacent Channel Rejection						
Adjacent channel (± 30 MHz) rejection - IEEE 802.11b (8% PER for 1024 octet PSDU with desired signal level as specified in Condition)	1 Mbps DSSS	-74 dBm	-	50	-	dB
	2 Mbps DSSS	-74 dBm	-	45	-	dB
Adjacent channel (± 25 MHz) rejection - IEEE 802.11b (8% PER for 1024 octet PSDU with desired signal level as specified in Condition)	5.5 Mbps DSSS	-70 dBm	-	43	-	dB
	11 Mbps DSSS	-70 dBm	-	40	-	dB
Adjacent channel (± 25 MHz) rejection - IEEE 802.11g (10% PER for 1000 octet PSDU with desired signal level as specified in Condition)	6 Mbps OFDM	-79 dBm	-	43	-	dB
	54 Mbps OFDM	-62 dBm	-	27	-	dB
Adjacent channel (± 25 MHz) rejection - IEEE 802.11n (10% PER for 4096 octet PSDU with desired signal level as specified in Condition)	HT20, MCS0	-79 dBm	-	43	-	dB
	HT20, MCS7	-61 dBm	-	21	-	dB
Adjacent channel (± 40 MHz) rejection - IEEE 802.11n (10% PER for 4096 octet PSDU with desired signal level as specified in Condition)	HT40, MCS0	-76 dBm	-	TBD	-	dB
	HT40, MCS7	-58 dBm	-	TBD	-	dB
Adjacent channel (± 20 MHz) rejection - IEEE 802.11ax (10% PER for 4096 octet PSDU with desired signal level as specified in Condition)	HE20, MCS0	-79 dBm	-	43	-	dB
	HE20, MCS7	-61 dBm	-	26	-	dB
Adjacent channel (± 40 MHz) rejection - IEEE 802.11ax (10% PER for 4096 octet PSDU with desired signal level as specified in Condition)	HE40, MCS0	-76 dBm	-	TBD	-	dB
	HE40, MCS7	-58 dBm	-	TBD	-	dB

Parameter	Condition	Min.	Typ.	Max.	Unit
Spurious Emissions					
Spurious emissions	< 1 GHz	-	-60	-	dBm
	> 1 GHz	-	-50	-	dBm

5.14 WLAN RF Transmitter Characteristics

Measured with T = 25 °C, VBAT = 3.3 V unless otherwise stated.

Parameter	Condition	Min.	Typ.	Max.	Unit
General					
Frequency range	-	2412	-	2484	MHz
TX Power					
TX power - IEEE 802.11b (SEM compliant)	1 Mbps DSSS	-	21	-	dBm
	11 Mbps DSSS	-	21	-	dBm
TX power - IEEE 802.11g (EVM compliant)	6 Mbps OFDM	-	18	-	dBm
	54 Mbps OFDM	-	18	-	dBm
TX power - IEEE 802.11n (EVM compliant)	HT20, MCS0	-	17	-	dBm
	HT20, MCS7	-	17	-	dBm
	HT40, MCS0	-	17	-	dBm
	HT40, MCS7	-	16	-	dBm
TX power - IEEE 802.11ax (EVM compliant)	HE20, MCS0	-	17	-	dBm
	HE20, MCS7	-	17	-	dBm
	HE40, MCS0	-	17	-	dBm
	HE40, MCS7	-	16	-	dBm
Spurious Emissions					
Spurious emissions (at maximum output power)	< 1 GHz	-	-50	-	dBm
	> 1 GHz	-	-45	-	dBm

5.15 Bluetooth LE RF Receiver Characteristics

Measured with T = 25 °C, VBAT = 3.3 V unless otherwise stated.

Parameter	Condition	Min.	Typ.	Max.	Unit
General					
Frequency range	-	2402	-	2480	MHz
Bluetooth LE 1 Mbps					
Sensitivity	30.8% PER	-	-97	-	dBm
Maximum input level	30.8% PER	-	0	-	dBm
C/I co-channel	-	-	8	-	dB
C/I 1 MHz adjacent channel	-	-	0	-	dB
C/I -1 MHz adjacent channel	-	-	0	-	dB
C/I 2 MHz adjacent channel	-	-	-26	-	dB
C/I -2 MHz adjacent channel	-	-	-27	-	dB
C/I 3 MHz adjacent channel	-	-	-28	-	dB
C/I -3 MHz adjacent channel	-	-	-29	-	dB
C/I > 3 MHz adjacent channel	-	-	-50	-	dB
C/I < -3 MHz adjacent channel	-	-	-50	-	dB
Out-of-band blocking	30–2000 MHz	-10	-	-	dBm
	2003–2399 MHz	-12	-	-	dBm
	2484–2997 MHz	-12	-	-	dBm
	3000 MHz–12.75 GHz	-2	-	-	dBm
Intermodulation	-	-	TBD	-	dBm
Bluetooth LE 2 Mbps					
Sensitivity	30.8% PER	-	-94	-	dBm
Maximum input level	30.8% PER	-	0	-	dBm
C/I co-channel	-	-	7	-	dB
C/I 2 MHz adjacent channel	-	-	0	-	dB
C/I -2 MHz adjacent channel	-	-	3	-	dB

Parameter	Condition	Min.	Typ.	Max.	Unit
C/I 4 MHz adjacent channel	-	-	-26	-	dB
C/I -4 MHz adjacent channel	-	-	-30	-	dB
C/I 6 MHz adjacent channel	-	-	-30	-	dB
C/I -6 MHz adjacent channel	-	-	-39	-	dB
C/I > 6 MHz adjacent channel	-	-	-22	-	dB
C/I < -6 MHz adjacent channel	-	-	-22	-	dB
Out-of-band blocking	30–2000 MHz	-	-30	-	dBm
	2003–2399 MHz	-	-35	-	dBm
	2484–2997 MHz	-	-35	-	dBm
	3000 MHz–12.75 GHz	-	-17	-	dBm
Intermodulation	-	-	TBD	-	dBm
Bluetooth LE 125 kbps					
Sensitivity	30.8% PER	-	-102	-	dBm
Maximum input level	30.8% PER	-	0	-	dBm
C/I co-channel	-	-	3	-	dB
C/I 1 MHz adjacent channel	-	-	-15	-	dB
C/I -1 MHz adjacent channel	-	-	-16	-	dB
C/I 2 MHz adjacent channel	-	-	-34	-	dB
C/I -2 MHz adjacent channel	-	-	-40	-	dB
C/I 3 MHz adjacent channel	-	-	-42	-	dB
C/I -3 MHz adjacent channel	-	-	-43	-	dB
C/I > 3 MHz adjacent channel	-	-	-41	-	dB
C/I < -3 MHz adjacent channel	-	-	-42	-	dB
Bluetooth LE 500 kbps					
Sensitivity	30.8% PER	-	-99	-	dBm
Maximum input level	30.8% PER	-	0	-	dBm
C/I co-channel	-	-	5	-	dB
C/I 1 MHz adjacent channel	-	-	-2	-	dB

Parameter	Condition	Min.	Typ.	Max.	Unit
C/I -1 MHz adjacent channel	-	-	-3	-	dB
C/I 2 MHz adjacent channel	-	-	-30	-	dB
C/I -2 MHz adjacent channel	-	-	-31	-	dB
C/I 3 MHz adjacent channel	-	-	-31	-	dB
C/I -3 MHz adjacent channel	-	-	-40	-	dB
C/I > 3 MHz adjacent channel	-	-	-36	-	dB
C/I < -3 MHz adjacent channel	-	-	-36	-	dB

5.16 Bluetooth LE RF Transmitter Characteristics

Measured with T = 25 °C, VBAT = 3.3 V unless otherwise stated.

Parameter	Condition	Min.	Typ.	Max.	Unit	
General						
Frequency range	-	2402	-	2480	MHz	
TX power	-	-20	6	15	dBm	
Bluetooth LE 1 Mbps						
In-band emissions	±2 MHz offset	-	-	-47	dBm	
	±3 MHz offset	-	-	-49	dBm	
	>±3 MHz offset	-	-	-50	dBm	
Modulation characteristics	Δf_{1avg}	-	225	245	275	kHz
	Δf_{2max}	-	185	235	-	kHz
	$\Delta f_{2avg}/\Delta f_{1avg}$	-	0.8	0.93	-	-
Carrier frequency offset and drift	Max $ f_n $ n = 0, 1, 2, 3...k	-	-	3	150	kHz
	Max $ f_0 - f_n $ n = 2, 3, 4...k	-	-	2.5	50	kHz
	$ f_1 - f_0 $	-	-	2	23	kHz
	Max $ f_n - f_{n-5} $ n = 6, 7, 8...k	-	-	2.5	20	kHz/50 μ s
Bluetooth LE 2 Mbps						
In-band emissions	±4 MHz offset	-	-	-50	dBm	

Parameter	Condition	Min.	Typ.	Max.	Unit	
	± 5 MHz offset	-	-	-51	-	dBm
	$> \pm 5$ MHz offset	-	-	-52	-	dBm
Modulation characteristics	Δf_{1avg}	-	-	488	-	kHz
	Δf_{2max}	-	-	469	-	kHz
	$\Delta f_{2avg}/\Delta f_{1avg}$	-	-	0.93	-	-
Carrier frequency offset and drift	$\text{Max } f_n _{n=0, 1, 2, 3\dots k}$	-	-	3	150	kHz
	$\text{Max } f_0 - f_n _{n=2, 3, 4\dots k}$	-	-	2.5	50	kHz
	$ f_1 - f_0 $	-	-	1.5	23	kHz
	$\text{Max } f_n - f_{n-5} _{n=6, 7, 8\dots k}$	-	-	2.5	20	kHz/50 μ s
Bluetooth LE 125 kbps						
In-band emissions	± 2 MHz offset	-	-	-47	-	dBm
	± 3 MHz offset	-	-	-49	-	dBm
	$> \pm 3$ MHz offset	-	-	-50	-	dBm
Modulation characteristics	Δf_{1avg}	-	225	245	275	kHz
	Δf_{1max}	-	185	246	-	kHz
Carrier frequency offset and drift	$\text{Max } f_n _{n=0, 1, 2, 3\dots k}$	-	-	1.5	150	kHz
	$\text{Max } f_0 - f_n _{n=1, 2, 3\dots k}$	-	-	1.5	50	kHz
	$ f_0 - f_3 $	-	-	1.5	19.2	kHz
	$ f_n - f_{n-3} _{n=7, 8, 9\dots k}$	-	-	1.5	19.2	kHz/48 μ s
Bluetooth LE 500 kbps						
In-band emissions	± 2 MHz offset	-	-	-47	-	dBm
	± 3 MHz offset	-	-	-49	-	dBm
	$> \pm 3$ MHz offset	-	-	-50	-	dBm

5.17 AUX ADC Characteristics

Parameter	Condition	Min.	Typ.	Max.	Unit
Conversion clock	-	0.2	-	13	MHz
Conversion time	-	-	16	-	Cycle
V_{REF}	Internal	-	1.1	-	V
	External	-	VIO/3	-	V
Input voltage range	-	0	-	$V_{REF} * N^{(1)}$	V
Input impedance	-	10	-	-	$M\Omega$
Input capacitance (Cs)	-	-	1	-	pF
DNL	-	-1	-	3	LSB
INL	-	-5	-	5	LSB
ENOB	-	-	10	-	Bit
SNDR	-	-	62	-	dB
SFDR	-	-	77	-	dB
$T_{STARTUP}$	-	-	5	-	μs
Current consumption	-	-	200	-	μA

(1) N is the input voltage division factor. N=1, 2, 3, or 4.

6. Package Information

Figure 6-1 QFN40 5 x 5 mm Package Outline

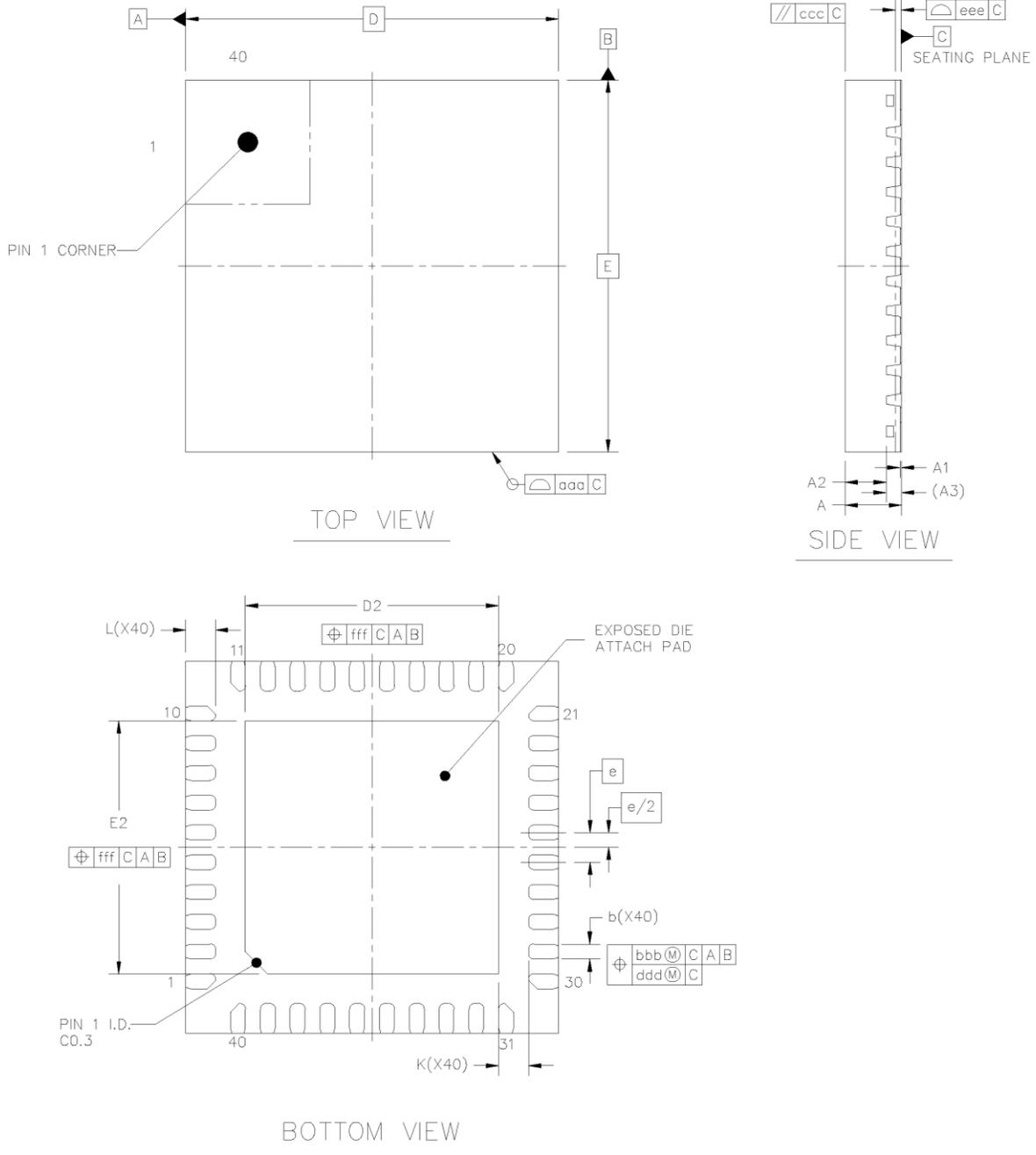
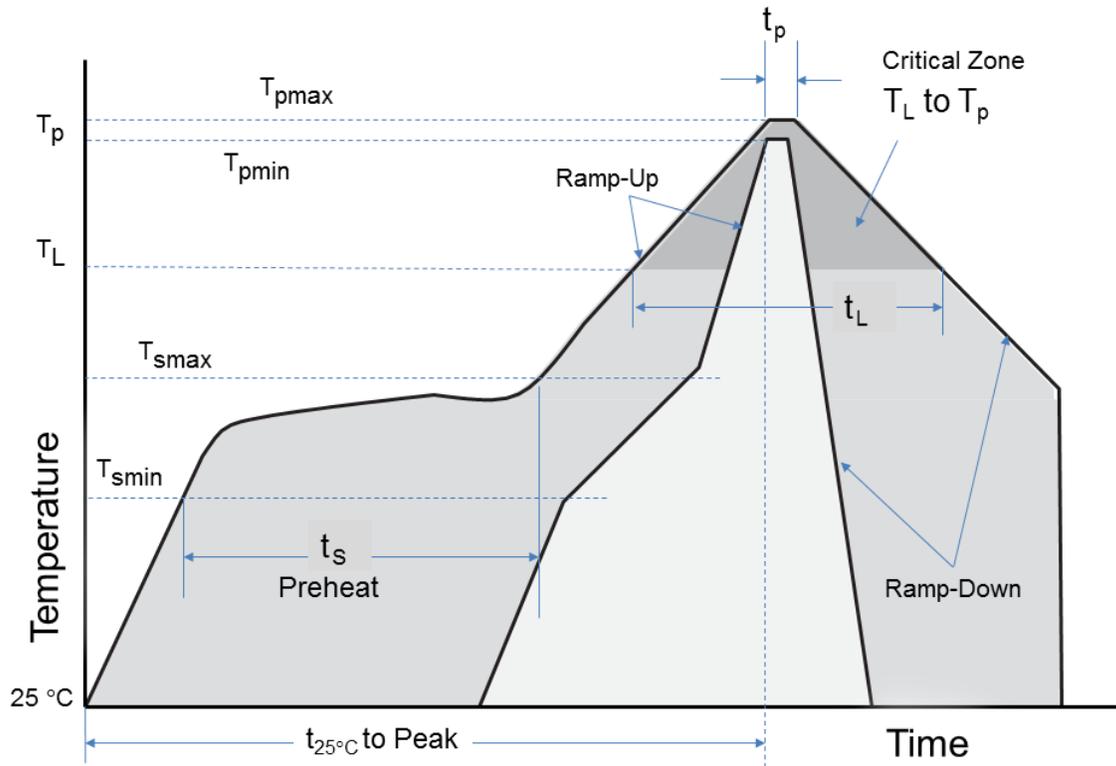


Table 6-1 QFN40 Package Dimensions

Symbol	Dimensions in Millimeters		
	Min.	Nom.	Max.
A	0.70	0.75	0.80
A1	0.00	0.02	0.05
A2	-	0.55	-
A3	0.203 REF		
b	0.15	0.20	0.25
D	5.00 BSC		
E	5.00 BSC		
e	0.40 BSC		
D2	3.30	3.40	3.50
E2	3.30	3.40	3.50
L	0.30	0.40	0.50
K	0.40 REF		
aaa	0.10		
ccc	0.10		
eee	0.08		
bbb	0.07		
ddd	0.05		
fff	0.10		

7. Reflow Soldering Profile

Figure 7-1 Reflow Soldering Profile



Profile Feature		Specification
Average ramp-up rate (T_{smax} to T_p)		3 °C/s max.
Preheat	Temperature min. (T_{smin})	150 °C
	Temperature max. (T_{smax})	200 °C
	Time (t_s)	60 s to 180 s
Time maintained above	Temperature (T_L)	217 °C
	Time (t_L)	60 s to 150 s
Peak/classification temperature (T_p)		260 °C
Time within 5 °C of actual peak temperature (t_p)		20 s to 40 s

Profile Feature	Specification
Ramp-down rate	6 °C/s max.
Time 25 °C to peak temperature	8 minutes max.

RoHS Compliant

The product does not contain lead, mercury, cadmium, hexavalent chromium, PBB, PBDE, DEHP, BBP, DBP, or DIBP content in accordance with EU RoHS Directive (EU) 2015/863 amending Annex II to Directive 2011/65/EU.

ESD Sensitivity

Integrated circuits are ESD sensitive and can be damaged by static electricity. Proper ESD techniques should be used when handling these devices.



Moisture Sensitivity Level

The product is qualified to moisture sensitivity level MSL3 in accordance with IPC/JEDEC J-STD-020.

8. Ordering Information

Figure 8-1 Ordering Code Scheme

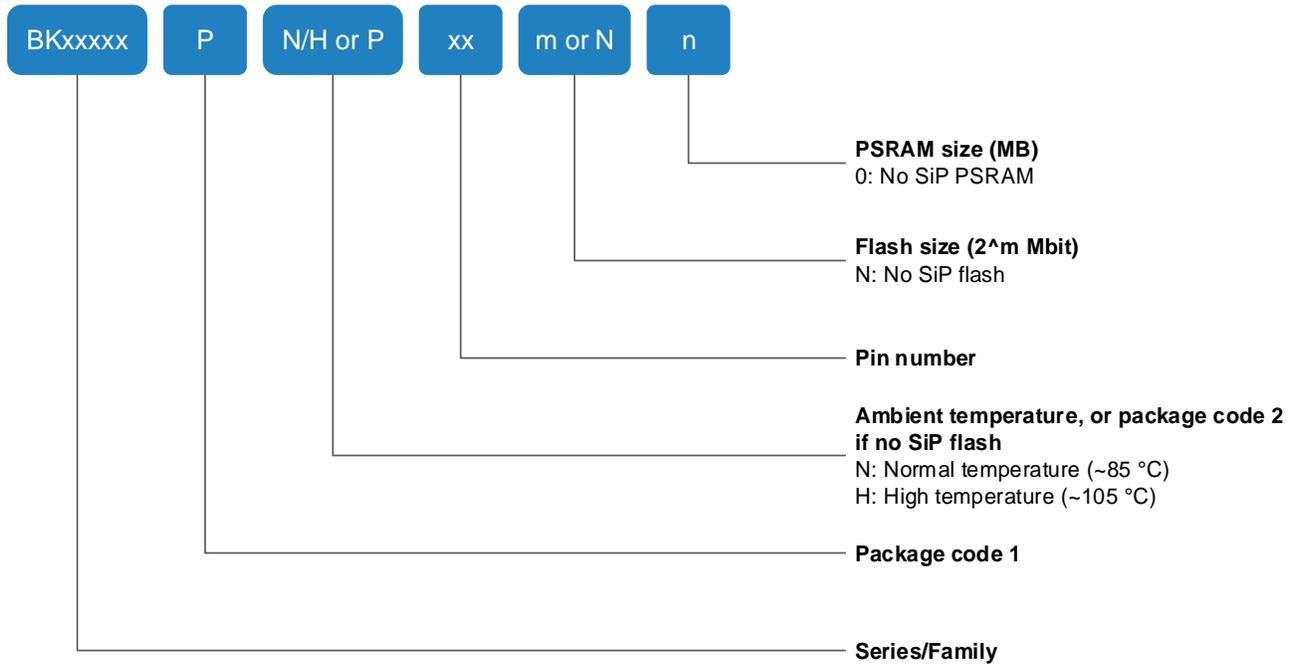


Table 8-1 Ordering Information

Ordering Code	Package	SiP ⁽¹⁾ Flash	SiP PSRAM	Packing	Minimum Ordering Qty (MOQ)
BK7236MQH4050	5 mm x 5 mm QFN40	4 MB	-	Tape and Reel	3000

(1) A system in a package (SiP) refers to flash/PSRAM enclosed in the package.



Revision History

Version	Date	Description
1.0	2025/1/6	Initial release

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